Expand your Working Range
Extended Stencils with LPKF StencilLaser G 6080
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New product requirements demand new manufacturing methods: Following a system upgrade, the LPKF StencilLaser G 6080’s processing capabilities have been extended to stencils of up to 1,600 mm in length, from a previous limit of 800 mm. This yields new product options such as stencil manufacturing for replacing conventional fluorescent tubes with LEDs.

With its StencilLaser G 6080, LPKF holds a top position in the global market – and is defending it through continuous advancements. After publishing methods for manufacturing step stencils, the company is now expanding the working range.

The StencilLaser G 6080 can easily be extended to hold extra-long frames. And the advantages of this? The cutting area is enlarged to 1,600 mm, without compromising laser class 1 for normal operation, and fine and ultrafine dust filtering. Additional protective devices are hence not needed. All other performance characteristics remain unchanged. Data processing for the extended stencils is controlled via the supplied CAM software. System modification and operator training can be done in less than three hours.

After the modification, the StencilLaser can process an effective area of 600 x 1,600 mm. The bulge in the rear cover increases the depth of the StencilLaser from 1,570 to 2,070 mm.

Due to the quick modification and operator training lost production time is kept to a minimum. Extended stencil production is performed in two steps: First, the front half of the stencil is cut. Then the frame is rotated and the second half is cut. The laser system thereby utilizes the automated alignment feature and places both cutting fields next to each other with a tolerance of just 20 microns.

An effective cutting area of 600 x 1,600 mm combined with 740 x 1,800 mm large frames simplifies numerous manufacturing processes, for instance, for large retrofit LED lights.

### Technical Data: Extended Cutting Range

<table>
<thead>
<tr>
<th>Max. cutting area (W x H)</th>
<th>600 mm x 1,600 mm</th>
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<tr>
<td>Max. frame size (W x H x D)</td>
<td>740 mm x 1,800 mm x 40 mm</td>
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